Low-Cost Copper Conductive Inks (Yissum)

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Novel formulation enables printing on low-cost plastic substrates

Categories	Nanoparticles, Nanoprocesses, Nano printing, Nano inks
Development Stage	Proof of concept of general technology
Patent Status	PCT application filed

Highlights

- Enables the printing of low-cost conductive patterns.
- Low decomposition temperature – enables printing on temperature-sensitive, low-cost plastic substrates
- Highly stable ink – no aggregation and no oxidation problems
- Simple process and environment friendly solvents

Our Innovation

Currently used conductive inks are very expensive (silver based inks), are not stable in air (copper based inks) and require high sintering temperature. Here we present new copper inks with high metal load and low decomposition temperature (